

## **SSC8632GN4**

### **N- and P-Channel Complementary, MOSFET**

#### ➤ Features

##### **N-Channel**

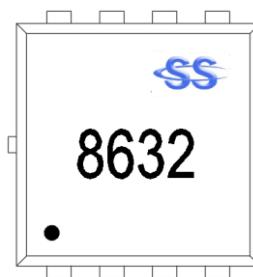
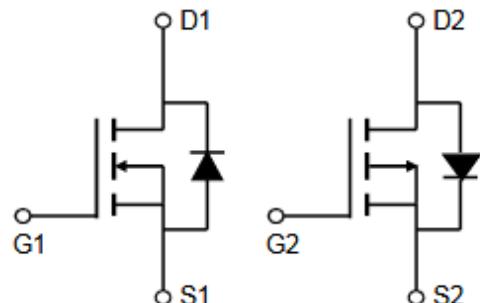
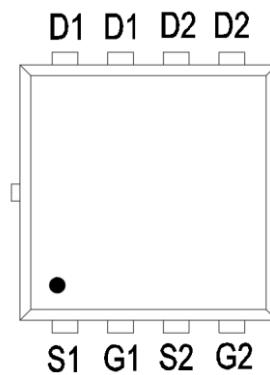
VDS	VGS	RDS <sub>ON</sub> Typ.	ID
30V	$\pm 20V$	16mR@10V	8A
		20mR@4V5	

##### **P-Channel**

VDS	VGS	RDS <sub>ON</sub> Typ.	ID
-30V	$\pm 20V$	42mR@-10V	-6A
		60mR@-4V5	

#### ➤ Pin configuration

##### Top view



Marking

#### ➤ Applications

- Inverter
- CCFL Driver

#### ➤ Ordering Information

Device	Package	Shipping
SSC8632GN4	PDFN3.3X3.3	5000/Reel

➤ **Absolute Maximum Ratings( $T_A=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter		N-Channel	P-Channel	Unit
$V_{DSS}$	Drain-to-Source Voltage		30	-30	V
$V_{GSS}$	Gate-to-Source Voltage		$\pm 20$	$\pm 20$	V
$I_D$	Continuous Drain Current <sup>a</sup>	TA=25°C	8	-6	A
		TA=70°C	6	-5	A
$I_{DM}$	Pulsed Drain Current <sup>b</sup>		32	-24	A
$P_{DSM}$	Power Dissipation <sup>a</sup>	TC=25°C	20		W
$I_{AS}$	Avalanche Current <sup>b</sup> L=0.1mH Single Pulse		20	18	A
$E_{AS}$	Avalanche Energy <sup>b</sup> L=0.1mH Single Pulse		20	16	mJ
$P_D$	Power Dissipation <sup>c</sup>	TA=25°C	2.6		W
		TA=70°C	1.6		W
$T_J$	Operation junction temperature		-55 to 150		°C
$T_{STG}$	Storage temperature range		-55 to 150		°C

➤ **Thermal Resistance Ratings( $T_A=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Typical	Maximum	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance <sup>a</sup>		48	°C/W
$R_{\theta JC}$	Junction-to-Case Thermal Resistance		6.25	

Note:

- The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz.copper,in a still air environment with  $T_A=25^\circ\text{C}$ .The value in any given application depends on the user is specific board design. The current rating is based on the  $t \leq 10\text{s}$  thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.
- The power dissipation  $P_D$  is based on  $T_{J(MAX)}=150^\circ\text{C}$ , using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.

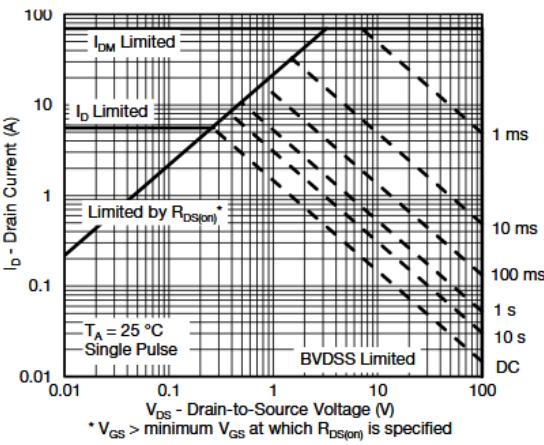
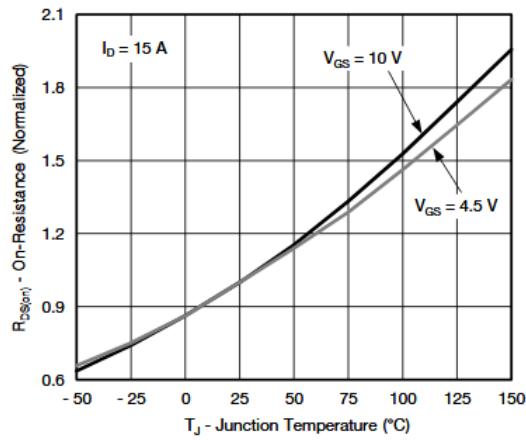
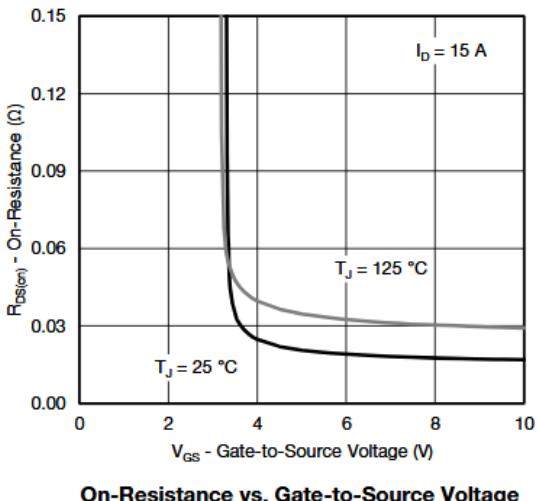
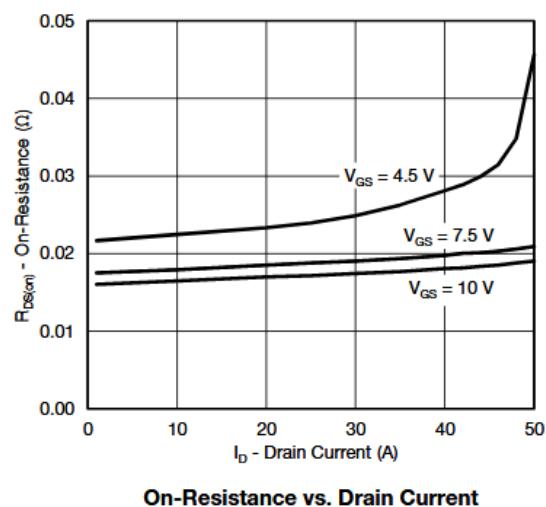
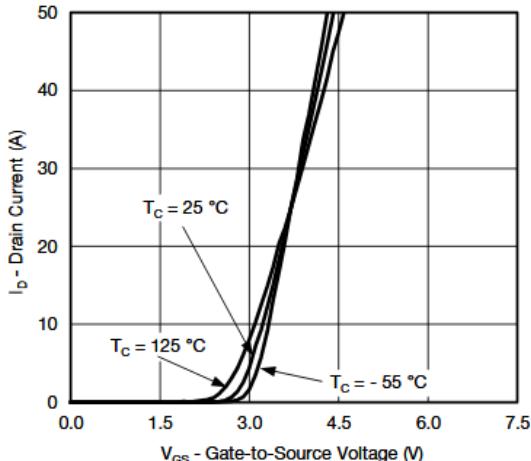
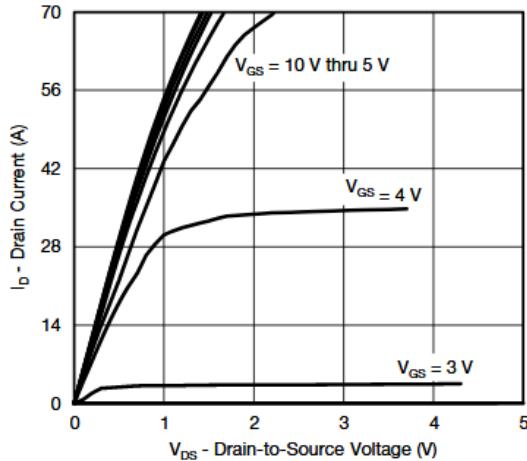
➤ Electronics Characteristics( $T_A=25^\circ C$  unless otherwise noted)

Symbol	Parameter	Test Conditions		Min	Typ.	Max	Unit	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, ID=250\mu A$	N-CH	30			V	
		$V_{GS}=0V, ID=-250\mu A$	P-CH	-30				
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, ID=250\mu A$	N-CH	1	1.4	3	V	
		$V_{DS}=V_{GS}, ID=-250\mu A$	P-CH	-1	-1.5	-3		
$R_{DS(on)}$	Drain-Source On- Resistance	$V_{GS}=10V, ID=6A$	N-CH		16	24	mR	
		$V_{GS}=10V, ID=-4A$	P-CH		42	60		
		$V_{GS}=4.5V, ID=5A$	N-CH		20	32		
		$V_{GS}=-4.5V, ID=-3A$	P-CH		60	80		
$I_{DSS}$	Zero Gate Voltage	$V_{DS}=24V, V_{GS}=0V$	N-CH			1	uA	
	Drain Current	$V_{DS}=-24V, V_{GS}=0V$	P-CH			-1		
$I_{GSS}$	Gate-Source leak current	$V_{GS}=\pm 20V, V_{DS}=0V$	N-CH			$\pm 100$	nA	
		$V_{GS}=\pm 20V, V_{DS}=0V$	P-CH			$\pm 100$		
$G_{FS}$	Forward Transconductance	$V_{DS}=5V, ID=6A$	N-CH		10		S	
		$V_{DS}=-5V, ID=-4A$	P-CH		15			
$V_{SD}$	Forward Voltage	$V_{GS}=0V, IS=1A$	N-CH		0.78	1.3	V	
		$V_{GS}=0V, IS=-1A$	P-CH		-0.77	-1.3		
$C_{iss}$	Input Capacitance	<b>NMOS:</b> $V_{DS}=15V,$ $V_{GS}=0V, f=1MHz$ <b>PMOS:</b> $V_{DS}=-15V,$ $V_{GS}=0V, f=1MHz$	N-CH		540		pF	
			P-CH		550			
$C_{oss}$	Output Capacitance		N-CH		82			
			P-CH		87			
$C_{rss}$	Reverse Transfer Capacitance		N-CH		28			
			P-CH		31			

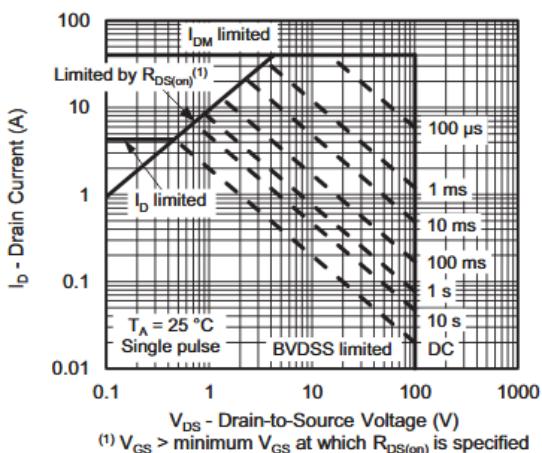
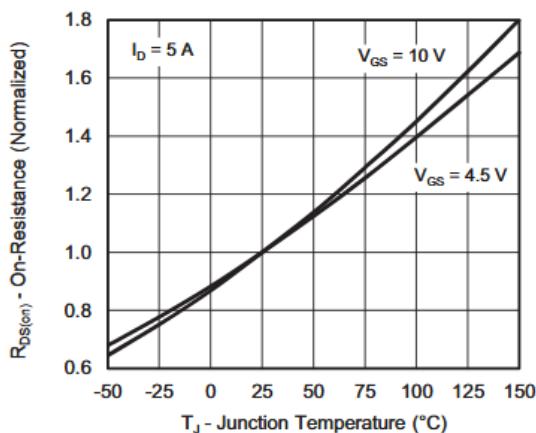
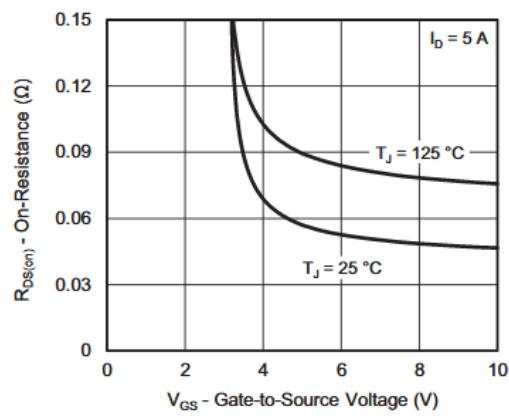
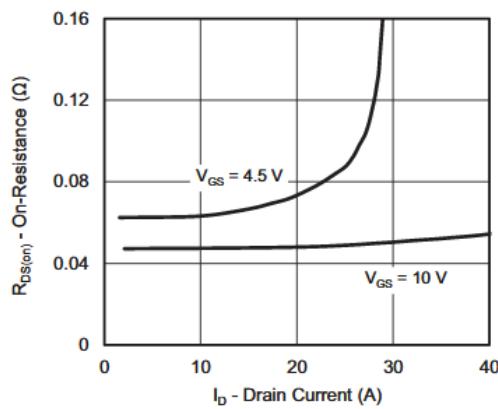
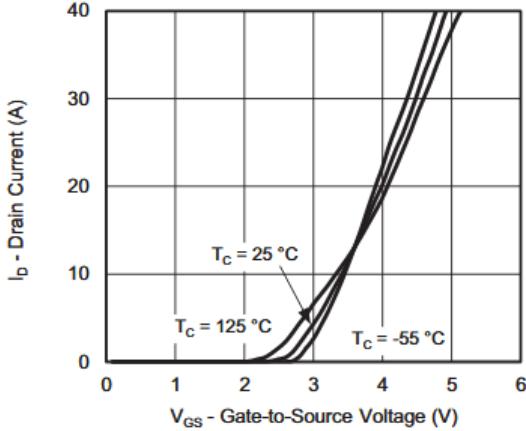
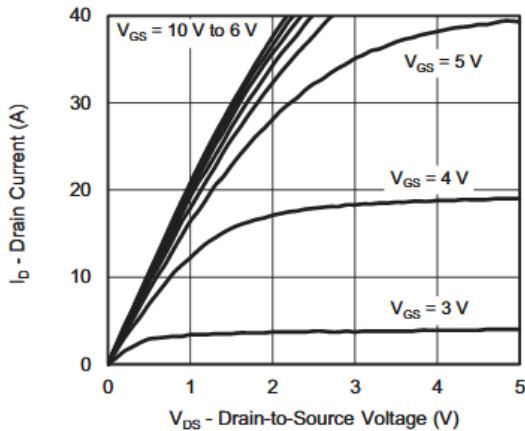


Qg	Total Gate Charge	<b>NMOS:</b> VDS=15V, VGS=10V, ID=8A  <b>PMOS:</b> VDS=-15V, VGS=-10V, ID=-6A	N-CH		10		nC	
			P-CH		9			
Qgs	Gate Source Charge		N-CH		2.2			
			P-CH		2.3			
Qgd	Gate Drain Charge		N-CH		1.1			
			P-CH		1.9			
T <sub>D(ON)</sub>	Turn-on delay time		N-CH		9		ns	
			P-CH		13			
Tr	Rise time		N-CH		12			
			P-CH		15			
T <sub>D(OFF)</sub>	Turn-off delay time		N-CH		26			
			P-CH		21			
Tf	Fall time		N-CH		18			
			P-CH		14			

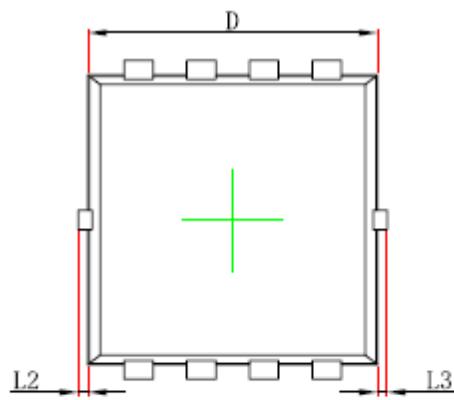
➤ **N-Channel Typical Characteristics**( $T_A=25^\circ\text{C}$  unless otherwise noted)



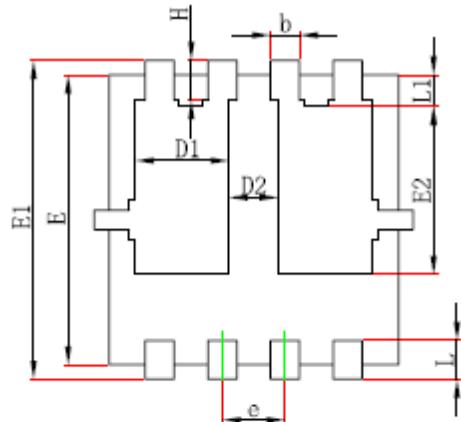
➤ **P-Channel Typical Characteristics**( $T_A=25^\circ\text{C}$  unless otherwise noted)



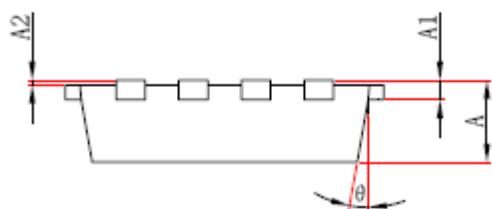
➤ Package Information



Top View  
[顶视图]



Bottom View  
[背视图]



Side View  
[侧视图]

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.650	0.850	0.026	0.033
A1	0.152 REF.		0.006 REF.	
A2	0~0.05		0~0.002	
D	2.900	3.100	0.114	0.122
D1	0.935	1.135	0.037	0.045
D2	0.280	0.480	0.011	0.019
E	2.900	3.100	0.114	0.122
E1	3.150	3.450	0.124	0.136
E2	1.535	1.935	0.060	0.076
b	0.200	0.400	0.008	0.016
e	0.550	0.750	0.022	0.030
L	0.300	0.500	0.012	0.020
L1	0.180	0.480	0.007	0.019
L2	0~0.100		0~0.004	
L3	0~0.100		0~0.004	
H	0.315	0.515	0.012	0.020
θ	9°	13°	9°	13°



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